CSD13202Q2 12-V N-Channel NexFET™ Power MOSFETs

1 Features

- Ultra-Low Q_g and Q_{gd}
- Low Thermal Resistance
- Avalanche Rated
- Lead-Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 2-mm × 2-mm Plastic Package

2 Applications

- Optimized for Load Switch Applications
- Storage, Tablets, and Handheld Devices
- Optimized for Control FET Applications
- Point of Load Synchronous Buck Converters

3 Description

This 12-V, 7.5-mΩ NexFET™ power MOSFET has been designed to minimize losses in power conversion and load management applications. The SON 2 × 2 offers excellent thermal performance for the size of the package.

Product Summary

T_A = 25°C		TYPICAL VAUE		UNIT
V_{DS}	Drain-to-Source Voltage	12		V
Q_g	Gate Charge Total (4.5 V)	5.1		nC
Q_{gd}	Gate Charge Gate-to-Drain	0.76		nC
$R_{DS(on)}$	Drain-to-Source On-Resistance	V_{GS} = 2.5 V	9.1	mΩ
		V_{GS} = 4.5 V	7.5	
$V_{GS(th)}$	Threshold Voltage	0.8		V

Device Information

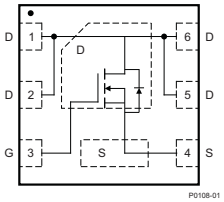
DEVICE	MEDIA	QTY	PACKAGE	SHIP
CSD13202Q2	7-Inch Reel	3000	SON 2.00-mm × 2.00-mm Plastic Package	Tape and Reel

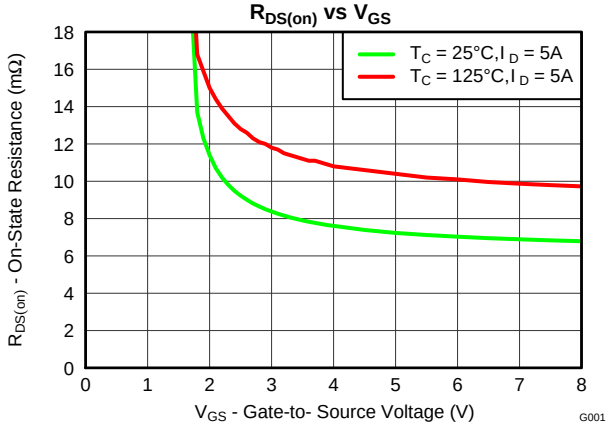
Absolute Maximum Ratings

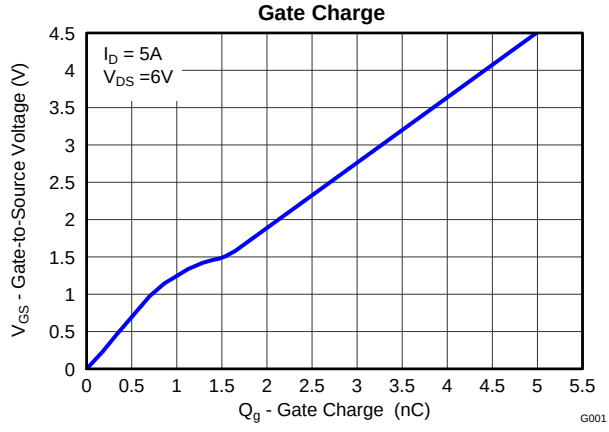
T_A = 25°C		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage	12	V
V_{GS}	Gate-to-Source Voltage	±8	V
I_D	Continuous Drain Current (Package Limit)	22	A
	Continuous Drain Current(1)	14.4	
I_{DM}	Pulsed Drain Current, T_A = 25°C(2)	76	A
P_D	Power Dissipation(1)	2.7	W
T_J, T_{STG}	Operating Junction, Storage Temperature	–55 to 150	°C
E_{AS}	Avalanche Energy, Single Pulse I_D = 20 A, L = 0.1 mH, R_G = 25 Ω	20	mJ

(1) $R_{\theta JA}$ = 45°C/W on 1-in^2 Cu (2-oz) on 0.06-in thick FR4 PCB.
(2) Pulse duration 10 µs, duty cycle ≤ 2%.

Top View







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4 Revision History

Changes from Original (September 2013) to Revision A **Page**

- Added *Device Information* table, *Specifications* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ... 1
- Updated the mechanical drawings ... 8

5 Specifications

5.1 Electrical Characteristics

T_A = 25°C, unless otherwise specified

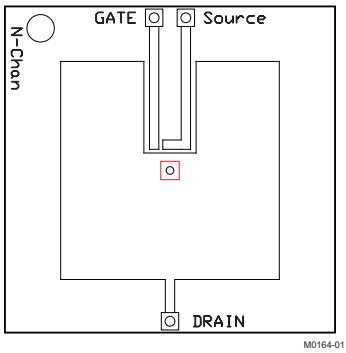
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
BV_{DSS}	Drain-to-source voltage	V_{GS} = 0 V, I_D = 250 µA	12			V
I_{DSS}	Drain-to-source leakage current	V_{GS} = 0 V, V_{DS} = 9.6 V			1	µA
I_{GSS}	Gate-to-source leakage current	V_{DS} = 0 V, V_{GS} = 8 V			100	nA
$V_{GS(th)}$	Gate-to-source threshold voltage	V_{DS} = V_{GS}, I_{DS} = 250 µA	0.58	0.80	1.10	V
$R_{DS(on)}$	Drain-to-source on-resistance	V_{GS} = 2.5 V, I_{DS} = 5 A		9.1	11.6	mΩ
		V_{GS} = 3 V, I_{DS} = 5 A		8.4	10.4	
		V_{GS} = 4.5 V, I_{DS} = 5 A		7.5	9.3	
g_{fs}	Transconductance	V_{DS} = 6 V, I_{DS} = 5 A		44		S
DYNAMIC CHARACTERISTICS						
C_{ISS}	Input capacitance	V_{GS} = 0V, V_{DS} = 6 V, f = 1 MHz		767	997	pF
C_{OSS}	Output capacitance			506	657	pF
C_{RSS}	Reverse transfer capacitance			43	56	pF
R_g	Series gate resistance			0.7	1.4	Ω
Q_g	Gate charge total (4.5 V)	V_{DS} = 6 V, I_{DS} = 5 A		5.1	6.6	nC
Q_{gd}	Gate charge gate-to-drain			0.76		nC
Q_{gs}	Gate charge gate-to-source			0.98		nC
$Q_{g(th)}$	Gate charge at Vth			0.57		nC
Q_{OSS}	Output charge	V_{DS} = 6 V, V_{GS} = 0 V		5.7		nC
$t_{d(on)}$	Turnon delay time	V_{DS} = 6 V, V_{GS} = 4.5 V, I_{DS} = 5 A R_G = 2 Ω		4.5		ns
t_r	Rise time			28		ns
$t_{d(off)}$	Turnoff delay time			11.0		ns
t_f	Fall time			13.6		ns
DIODE CHARACTERISTICS						
V_{SD}	Diode forward voltage	I_{DS} = 5 A, V_{GS} = 0 V		0.75	1	V
Q_{rr}	Reverse recovery charge	V_{DD} = 6 V, I_F = 5 A, di/dt = 200 A/µs		13		nC
t_{rr}	Reverse recovery time			28		ns

5.2 Thermal Characteristics

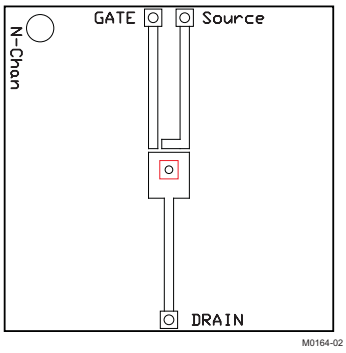
T_A = 25°C unless otherwise stated

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal resistance junction-to-case (1)			6.4	°C/W
$R_{\theta JA}$	Thermal resistance junction-to-ambient (1) (2)			60	°C/W

(1) $R_{\theta JC}$ is determined with the device mounted on a 1-in^2 (6.45-cm^2), 2-oz (0.071-mm) thick Cu pad on a 1.5-in × 1.5-in (3.81-cm × 3.81-cm), 0.06-in (1.52-mm) thick FR4 PCB. $R_{\theta JC}$ is specified by design, whereas $R_{\theta JA}$ is determined by the user's board design.
(2) Device mounted on FR4 material with 1-in^2 (6.45-cm^2), 2-oz (0.071-mm) thick Cu.



Max $R_{\theta JA}$ = 60 when mounted on 1 in^2 (6.45 cm^2) of 2-oz (0.071-mm) thick Cu.



Max $R_{\theta JA}$ = 210 when mounted on minimum pad area of 2-oz (0.071-mm) thick Cu.

5.3 Typical MOSFET Characteristics

T_A = 25°C unless otherwise stated

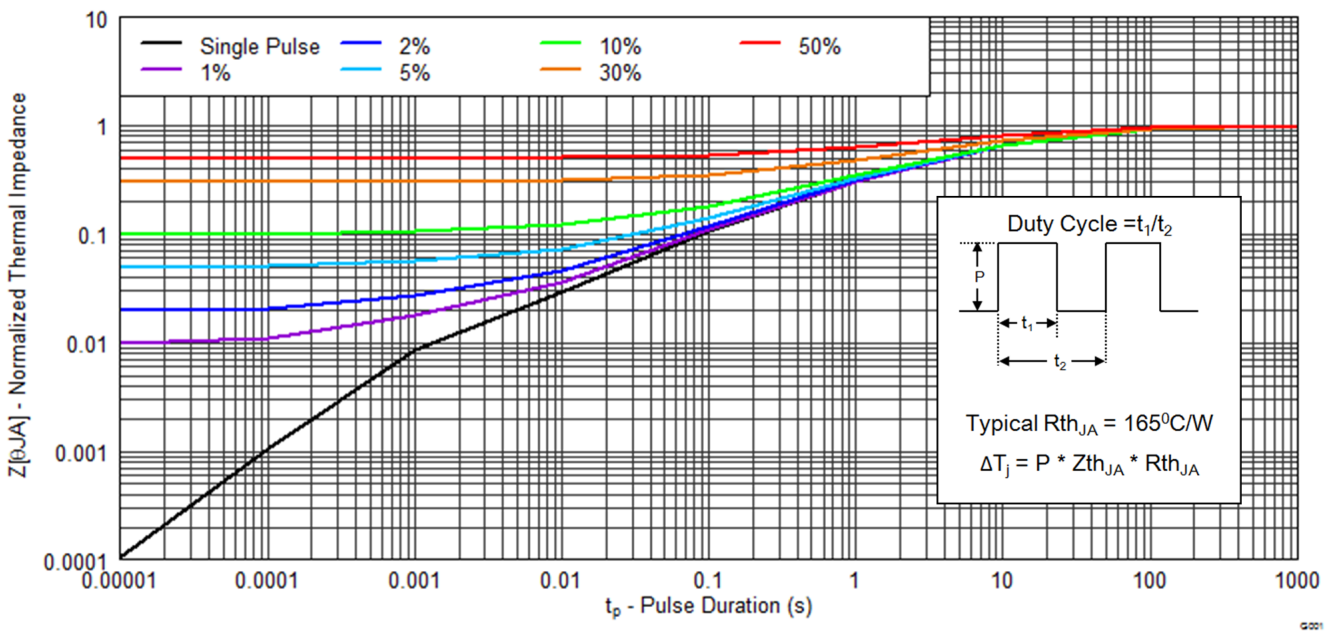


Figure 1. Transient Thermal Impedance

Typical MOSFET Characteristics (continued)

T_A = 25°C unless otherwise stated

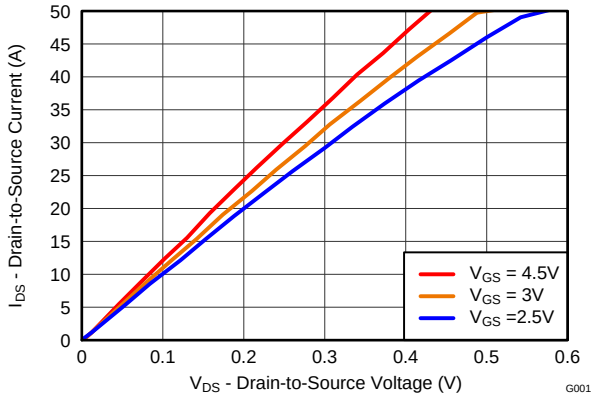


Figure 2. Saturation Characteristics

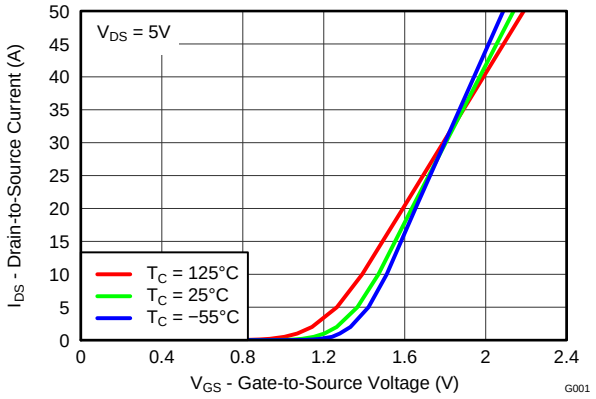


Figure 3. Transfer Characteristics

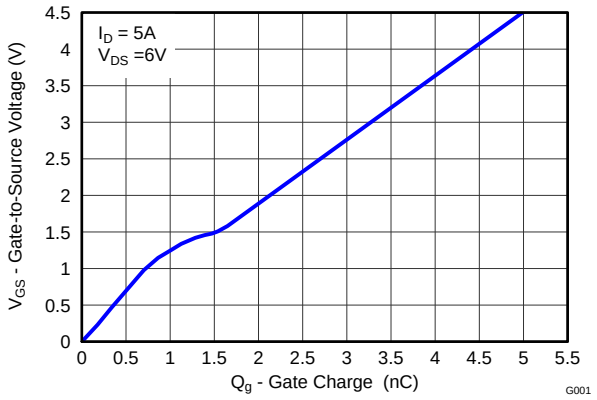


Figure 4. Gate Charge

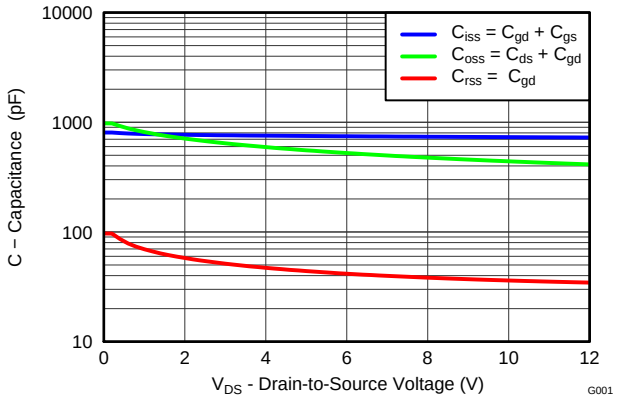


Figure 5. Capacitance

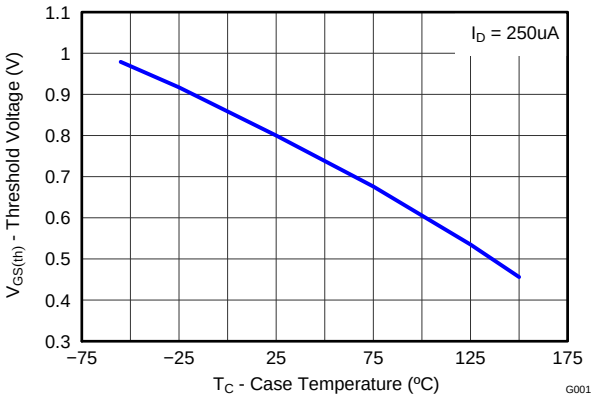


Figure 6. Threshold Voltage vs Temperature

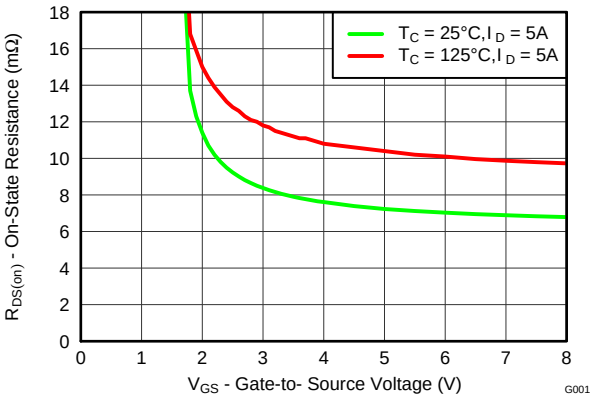


Figure 7. On-State Resistance vs Gate-to-Source Voltage

Typical MOSFET Characteristics (continued)

T_A = 25°C unless otherwise stated

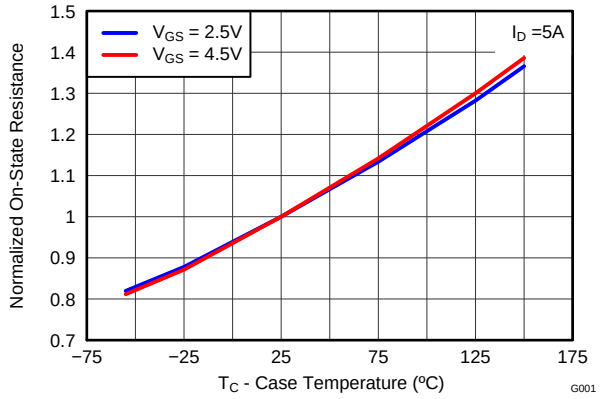


Figure 8. Normalized On-State Resistance vs Temperature

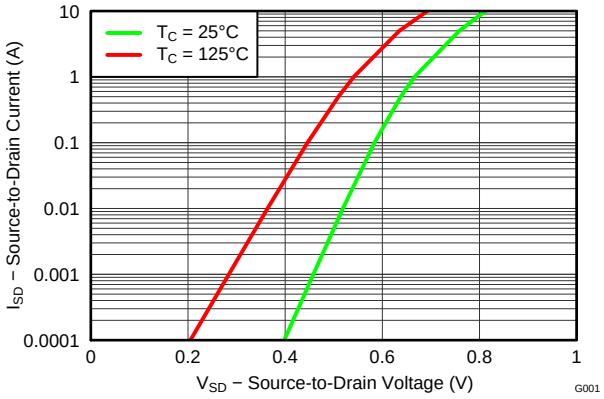


Figure 9. Typical Diode Forward Voltage

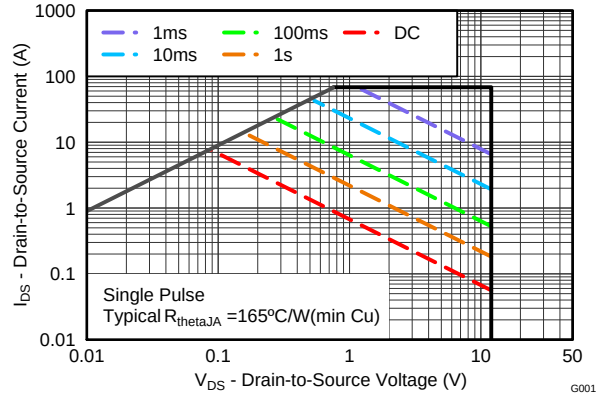


Figure 10. Maximum Safe Operating Area

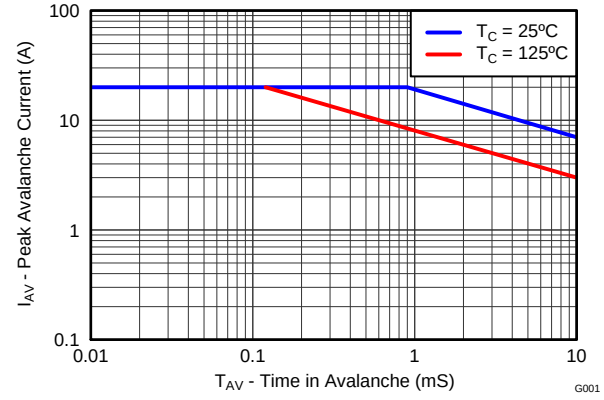


Figure 11. Single Pulse Unclamped Inductive Switching

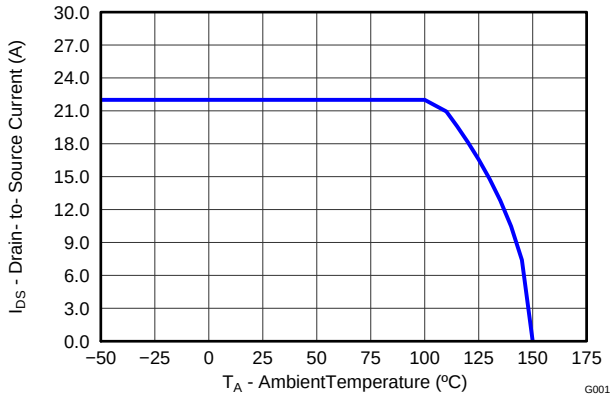


Figure 12. Maximum Drain Current vs Temperature

6 Device and Documentation Support

6.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

6.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.3 Trademarks

NexFET, E2E are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.

6.4 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.5 Glossary

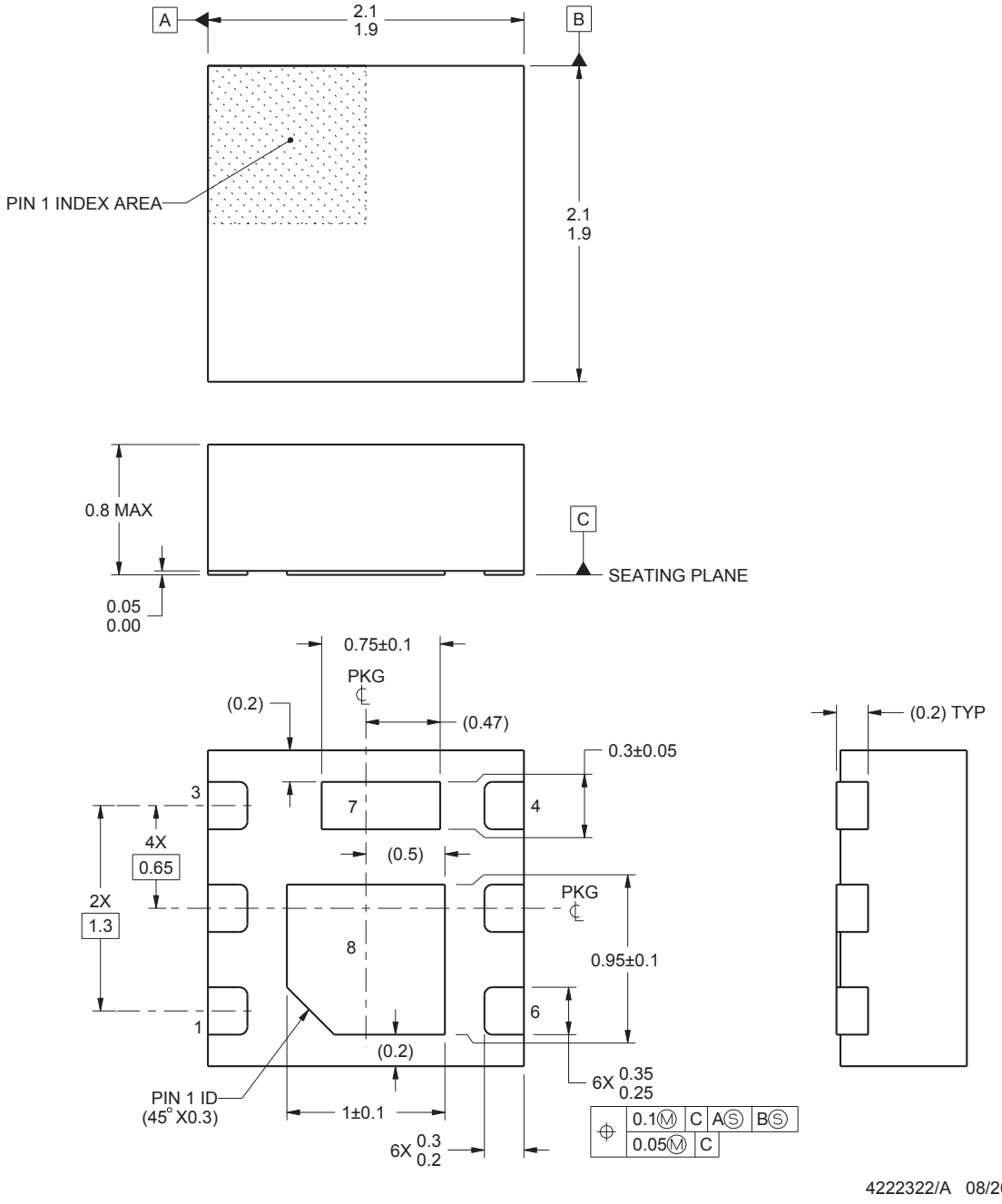
SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

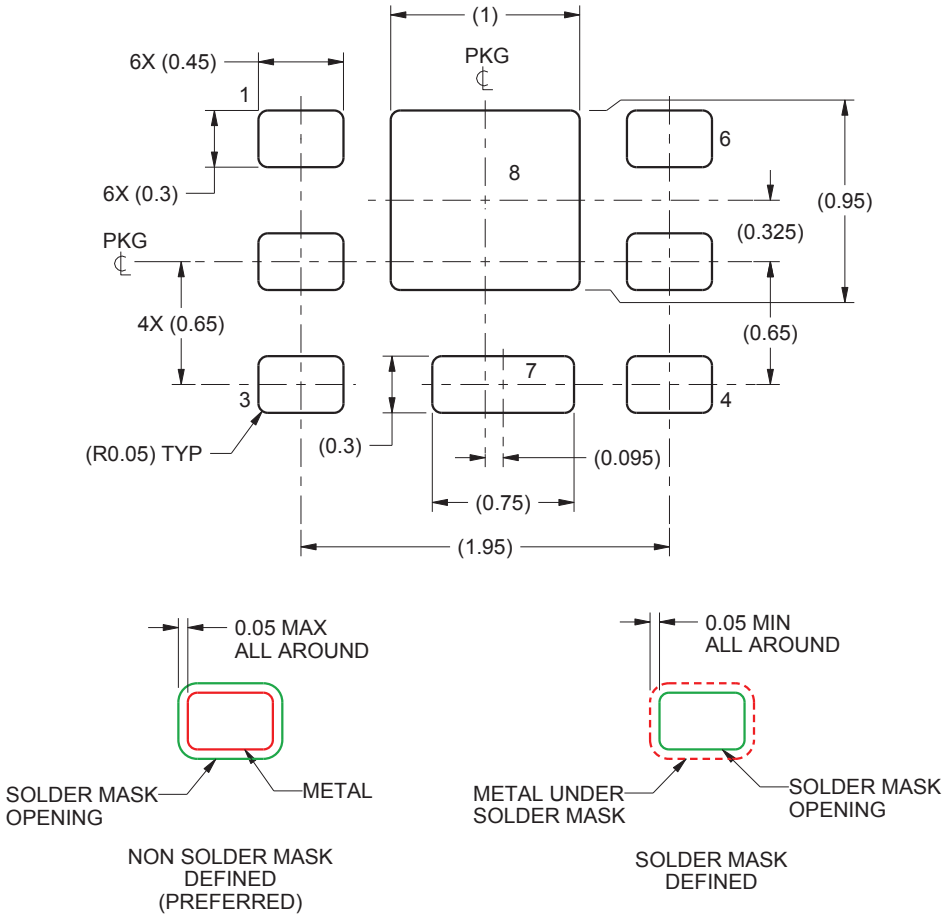
7.1 Q2 Package Dimensions



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for thermal and mechanical performance.

Q2 Package Dimensions (continued)

7.1.1 Recommended PCB Pattern

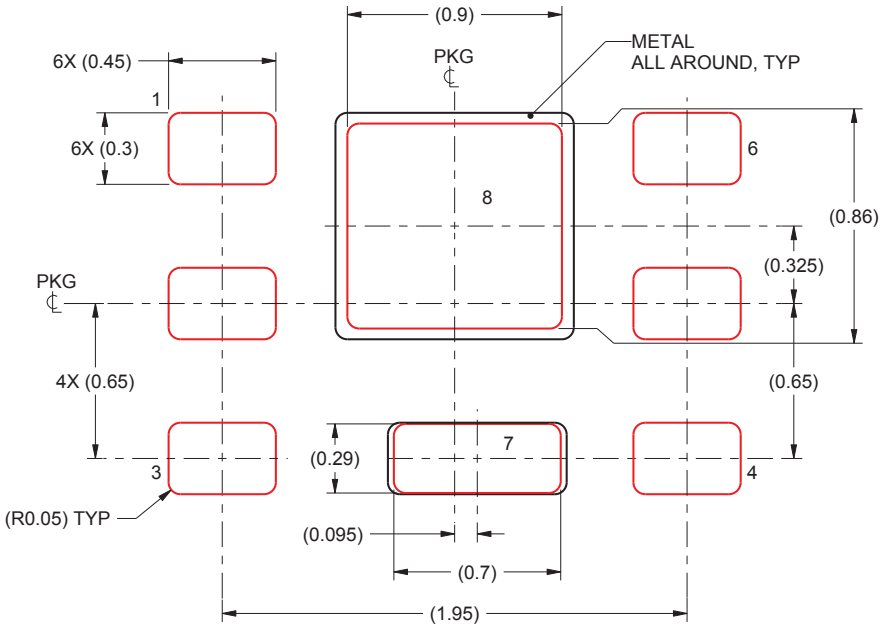


SOLDER MASK DETAILS

1. This package is designed to be soldered to a thermal pad on the board. For more information, see *QFN/SON PCB Attachment* (SLUA271).

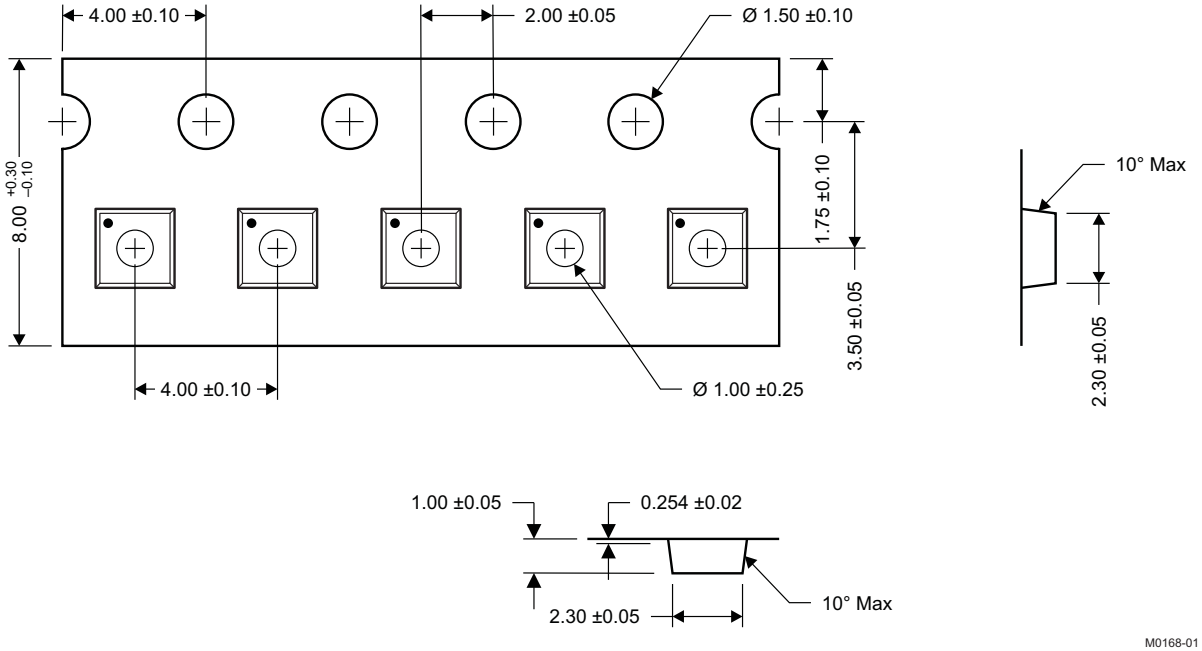
Q2 Package Dimensions (continued)

7.1.2 Recommended Stencil Pattern



1. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

7.2 Q2 Tape and Reel Information



Notes:
1. Measured from centerline of sprocket hole to centerline of pocket.
2. Cumulative tolerance of 10 sprocket holes is ±0.2.
3. Other material available.
4. Typical SR of form tape max 10^9 OHM/SQ.
5. All dimensions are in mm, unless otherwise specified.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CSD13202Q2	Active	Production	WSON (DQK) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 150	1322
CSD13202Q2.B	Active	Production	WSON (DQK) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 150	1322
CSD13202Q2G4.B	Active	Production	WSON (DQK) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 150	1322

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265